



MOUNTING FOOTPRINT (EACH PORT, TOP VIEW)

NOTES: UNLESS OTHERWISE SPECIFIED.

1. MATERIAL & FINISH: (127-0711-321)
 - 1.1 BODY: GOLD PLATED BERYLLIUM COPPER
 - 1.2 CONTACTS: GOLD PLATED BERYLLIUM COPPER
 - 1.3 INSULATORS: PTFE (TEFLON)
 2. ELECTRICAL SPECIFICATIONS:
 - 2.1 IMPEDANCE: 50 OHMS
 - 2.2 FREQUENCY RANGE: DC - 26.5 GHz
 - 2.3 VSWR: 1.25 MAX (0-18 GHz), 1.50 MAX (18-26.5 GHz)
 - 2.4 WORKING VOLTAGE: 335 VRMS MAX AT SEA LEVEL
 - 2.5 DIELECTRIC WITHSTANDING VOLTAGE: 500 VRMS MIN AT SEA LEVEL
 - 2.6 INSULATION RESISTANCE: 5000 MEGOHM MIN
 - 2.7 CONTACT RESISTANCE:
 - CENTER CONTACT: INITIAL 6.0 MILLIOHM MAX, AFTER ENVIRONMENTAL NOT APPLICABLE
 - OUTER CONDUCTOR: INITIAL 2.0 MILLIOHM MAX, AFTER ENVIRONMENTAL NOT APPLICABLE
 - 2.8 CORONA LEVEL: 190 VOLTS MIN AT 70,000 FEET
 - 2.9 RF HIGH POTENTIAL WITHSTANDING VOLTAGE: 325 VRMS MIN AT 4 & 7 MHz
 3. MECHANICAL SPECIFICATIONS:
 - 3.1 INTERFACE DESIGN: 1AW MIL-STD-348, FIG. 326-2, SERIES SMP, FULL DETENT
 - 3.2 ENGAGEMENT FORCE: 15 LBS MAX PER POSITION
 - 3.3 DISENGAGEMENT FORCE: 5 LBS MIN PER POSITION
 - 3.4 CONTACT RETENTION: 1.5 LBS MIN AXIAL
 - 3.5 DURABILITY: 100 CYCLES MIN
 4. ENVIRONMENTAL:
 - 4.1 (MEETS OR EXCEEDS THE APPLICABLE PARAGRAPH OF DSCC DWG NO. 94007)
 - 4.2 OPERATING TEMPERATURE: -65°C TO 165°C
 - 4.3 THERMAL SHOCK: MIL-STD-202, METHOD 107, CONDITION B, EXCEPT 165°C HIGH TEMP
 - 4.4 MECHANICAL SHOCK: MIL-STD-202, METHOD 213, CONDITION I
 - 4.5 CORROSION: MIL-STD-202, METHOD 101, CONDITION B
 - 4.6 VIBRATION: MIL-STD-202, METHOD 204, CONDITION D
 - 4.7 MOISTURE RESISTANCE: MIL-STD-202, METHOD 106, EXCEPT STEP 7B OMITTED
- △ REFERENCE DIMENSIONS FOR 50 OHM GROUND CPW LINE, USING ROGERS RO4003, 16 MIL HIGH FREQUENCY CIRCUIT BOARD SUBSTRATE:
- 5.1 TRACE WIDTH = 27.5 MILS
 - 5.2 GROUND GAPS = 10.5 MILS
 - 5.3 CONDUCTOR THICKNESS = 1.4 MILS (INCLUDES PLATING)
 - 5.4 MAINTAIN SOLID GROUND PLANE BELOW HF SUBSTRATE.
 - 5.5 PLACE 16 MIL DIA. GROUND VIAS ON BOTH SIDES OF COPLANAR WAVEGUIDE LINE AT 50 MIL INTERVALS ALONG ENTIRE LENGTH.
 - 5.6 IMMERSION GOLD PLATE (ENIG) ALL CONDUCTORS PER IPC-4552.
 - 5.7 ALL HOLES PLATED THRU ENTIRE CIRCUIT BOARD STACKUP.
 - 5.8 HOLE PATTERNS SYMMETRICAL ABOUT CENTER OF CPW TRACE.

6. PACKAGING:
 - 6.1 127-0711-321: 1 PER BAG

	THIS PRODUCT IS COMPLIANT WITH THE ROHS DIRECTIVE AND IS FREE OF HALOGENATED FLUORINE COMPOUNDS AND HEAVY METALS.	ASSEMBLY, MALE, FD, RAPC SURFACE MT, SMP, 4 POSITION
INTERMEDIATE DIMENSIONS IN ACCORDANCE WITH ASSE 100.5-2000.	DATE 11/16/15	1 OF 1